

Underfill Market 2016 Global In-Depth Investigation and Analysis Report to 2021

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PUNE, INDIA, December 20, 2016
/EINPresswire.com/ --

[Underfill is used to fill](#) space beneath a die and adhere to its carrier. They add structural strength, increase impact resistance, bolster thermal cycling resistance and improve overall reliability. Underfill can be found in a wide variety of applications including mobile phone, game console, computer, tablet PC and digital camera.

Scope of the Report:

This report focuses on the Underfill in Global market, especially in North America, Europe and Asia-Pacific, South America, Middle East and Africa. This report categorizes the market based on manufacturers, regions, type and application.

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Market Segment by Manufacturers, this report covers

Henkel

WON CHEMICAL

NAMICS

SUNSTAR



Hitachi Chemical
Fuji
Shin-Etsu Chemical
Bondline
AIM Solder
Zymet
Panacol-Elosol
Master Bond
DOVER
Darbond
HIGHTITE
U-bond

Market Segment by Regions, regional analysis covers
North America (USA, Canada and Mexico)
Europe (Germany, France, UK, Russia and Italy)
Asia-Pacific (China, Japan, Korea, India and Southeast Asia)
South America, Middle East and Africa

Market Segment by Type, covers
Semiconductor Underfills
Board Level Underfills

Market Segment by Applications, can be divided into
Industrial Electronics
Defense & Aerospace Electronics
Consumer Electronics (laptops, mobile phones, MP3 players, game consoles, digital cameras, etc.)

Automotive Electronics
Medical Electronics

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